

Notice of References Cited	Application/Control No. 10/700,782	Applicant(s)/Patent Under Reexamination KIM ET AL.	
	Examiner Edna Wong	Art Unit 1795	Page 1 of 1

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*	B	US-5,972,192	10-1999	Dubin et al.	205/101
*	C	US-5,421,987	06-1995	Tzanavaras et al.	205/133
*	D	US-3,963,588	06-1976	Glenn, Richard C.	205/96
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NON-PATENT DOCUMENTS

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	V	Ruythooren et al., "Electrodeposition for the Synthesis of Microsystems", J. Micromech. Microeng., Vol. 10 (no month, 2000), pp. 101-107.
	W	Buzhinskaya et al., "Behavior of Chlorine in the Electrolysis of Copper with Insoluble Anodes and Air Agitation of the Electrolyte at High Current Densities", Elektrokimiya (no month, 1970), Vol. 6, No. 3, pp. 315-317. ABSTRACT ONLY.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.